01-08-2003

Atty. Docket No.: 3887-0128P

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R HEET				
To the honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.				
1. Name of conveying party(ies):	2. Name and address of receiving party(ies)			
[FAMILY NAME (ALL CAPS), Given Name]	Name: HYNIX SEMICONDUCTOR INC.			
KIM, Hai-Won	Internal Address:			
CHAE, Su-Jin	Street Address: San 136-1, Ami-ri, Bubal-eub			
Additional name(s) of conveying party(ies) attached? YES NO	City: Ichon-shi State: Kyoungki-do ZIP: Country: REPUBLIC OF KOREA Postal Code: 467-860			
3. Nature of conveyance:				
Assignment Merger	Additional name(s) & address(es) attached? YES NO			
Security Agreement Change of Name				
Other:				
Execution Date: December 24, 2002				
4. Application number(s) or patent number(s):				
If this document is being filed together with a new application, the execution date of the application is: December 24, 2002				
A. Patent Application No(s).	B. Patent No.(s).			
NEW	B. Patent No.(s). /6/336303			
Additional numbers attached? YES NO				
5. Name and address of party to whom correspondence	6. Total No. of applications/patents involved: One (1)			
concerning document should be mailed:	7. Total fee (37 C.F.R. § 3.41): \$40.00			
Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP	 ☑ Enclosed ☑ Authorized to be charged to deposit account, if no fee attached. 			
Street Address: P.O. BOX 747 City: FALLS CHURCH State: VA ZIP: 22040-0747				
Country: USA	8. Deposit account number: <u>02-2448</u>			
	(Attach triplicate copy of this page if paying by deposit account)			
DO NOT USE THIS SPACE				
9. Statement and signature.				
Joseph A. Kolasch, #22,463 Name of Person Signing/Reg. No. December 30, 2002 Date The last of the second state of the second				
Total number of pages including cover sheet, attachments, and document: Three (3)				

JAK/jaf

(Rev. 02/11/02)

ATTORNEY DOCKET NO.

BIRCH, STEWART, KOLASCH & BIRCH, LLP UNITED STATES PATENT RIGHTS, OR UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

	Application No. NEW Filed December 30, 2002
nsert Name(s) of Inventor(s)	WHEREAS, KIM, HAI-WON and CHAE, SU-JIN
Const (DVI)	(hereinafter designated as the undersigned) has(have) invented certain new and useful improvements in METHOD FOR FABRICATING CONTACT PLUG WITH LOW CONTACT RESISTANCE
Insert Title of Invention	for which an application for Letters Patent of the United States of America has been executed by the undersigned(except in the case of a provisional application).
Insert Date of Signing of Application	On December 24, 2002 ; and WHEREAS, Hynix Semiconductor Inc.
Insert Name of Assignee	
Insert Address	Of San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea
of Assignee	Its hers, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefore in the United States of America and in any foreign countries.
CHECK BOK IF APPROPRIATE	NOW, THEREFORE, in consideration of the sum of Ten Dollars(\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has(have sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full an exclusive right to the said invention in the United States of America, its, territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be grante therefore in the United States of America, its territories, dependencies and possessions, and if the box above it designated, in any all foreign countries;
	And to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term of terms for which the same may be granted.

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PATENT REEL: 013623 FRAME: 0645

ATTORNEY DOCKET NO.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignce and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned and that he has(they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation or this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date_	December 24, 2002	Name Inventor(Signature)	Hai Won Kim
) Date	December 24, 2002	Name Inventor(Signature)	SuJin CHAZ
Date_		Name Inventor(Signature)	CHAE, SU-JIN
Date_		Name Inventor(Signature)	
Date_		Name Inventor(Signature)	

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PATENT RECORDED: 12/30/2002 REEL: 013623 FRAME: 0646